# BL-C34M/2G1H-41K-LC3.2

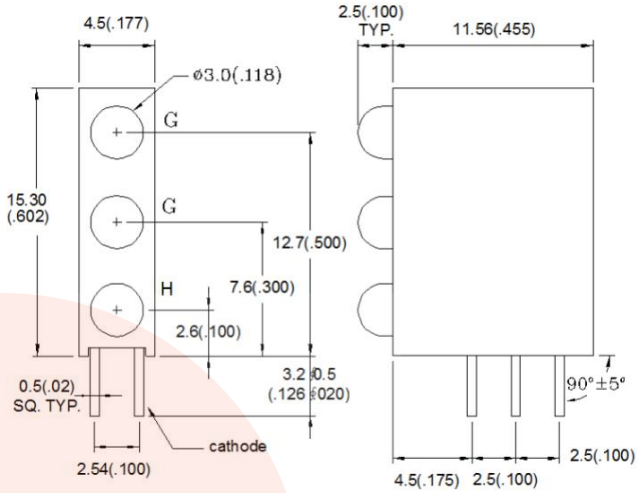
## ● Features:

1. Chip material: GaP/GaP(Green) and GaP/GaP (Red)
2. Emitted color : Green and Red
3. Lens Appearance :Green Diffused and Red Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
9. This product don't contained restriction substance, compliance RoHS standard.

## ● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

## ● Package dimensions




Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
3. Lead spacing is measured where the leads emerge from the package.
4. Specifications are subject to change without notice.

## ● Absolute Maximum Ratings(Ta=25℃)

| Parameter | Symbol | Green | Red | Unit |
|---|---|---|---|---|
| Power Dissipation | Pd | 80 | 80 | mW |
| Forward Current | $I_F$ | 30 | 30 | mA |
| Peak Forward Current*[1] | $I_{FP}$ | 150 | 150 | mA |
| Reverse Voltage | $V_R$ | 5 | | V |
| Operating Temperature | Topr | -40℃~85℃ | | |
| Storage Temperature | Tstg | -40℃~100℃ | | |
| Soldering Temperature | Tsol | 260℃max (for 5 seconds) | | |
| Hand Soldering Temperature | Tsol | 350℃max(for 3 seconds ) | | |

*[1]Condition for $I_{FP}$ is pulse of 1/10 duty and 0.1msec width.

## ● Electrical and optical characteristics(Ta=25℃)

| Parameter | Symbol | Condition | Color | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|---|
| Forward Voltage | $V_F$ | $I_F$=20mA | Green<br>Red | - | 2.2<br>2.3 | 2.6<br>2.6 | V |
| Luminous Intensity | Iv | $I_F$=20mA | Green<br>Red | - | 35<br>2.5 | - | mcd |
| Reverse Current | $I_R$ | $V_R$=5V | Green<br>ed | - | - | 100 | μA |
| Peak Wave Length | λ p | $I_F$=20mA | Green<br>Red | - | 568<br>700 | - | nm |
| Dominant Wave Length | λ d | $I_F$=20mA | Green<br>Red | 560<br>- | -<br>650 | 576<br>- | nm |
| Spectral Line Half-width | Δ λ | $I_F$=20mA | Green<br>Red | - | 30<br>100 | - | nm |
| Viewing Angle | $2\theta_{1/2}$ | $I_F$=20mA | Green<br>Red | - | 45 | - | deg |

## ● Typical Electro-Optical Characteristics Curves

Fig.1 Relative intensity vs. Wavelength

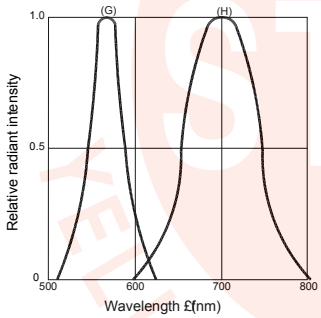



Fig.2 Forward current derating curve vs. Ambient temperature

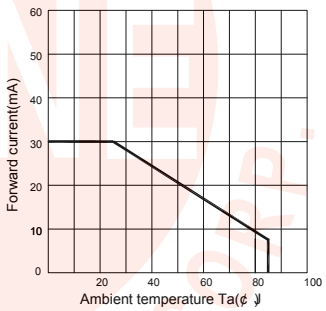



Fig.3 Forward current vs. Forward voltage

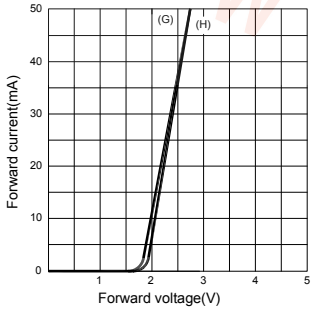



Fig.4 Relative luminous intensity vs. Ambient temperature

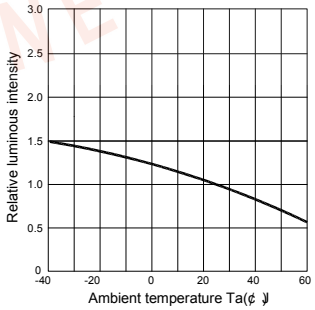



Fig.5 Relative luminous intensity vs. Forward current

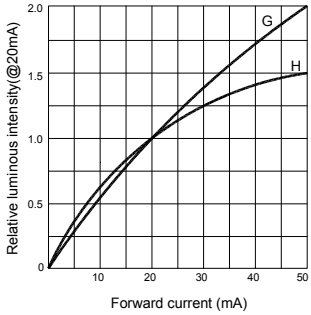
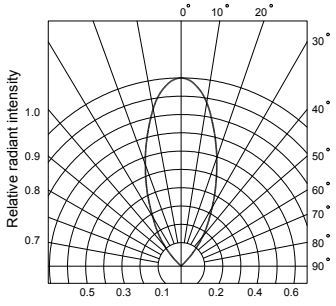
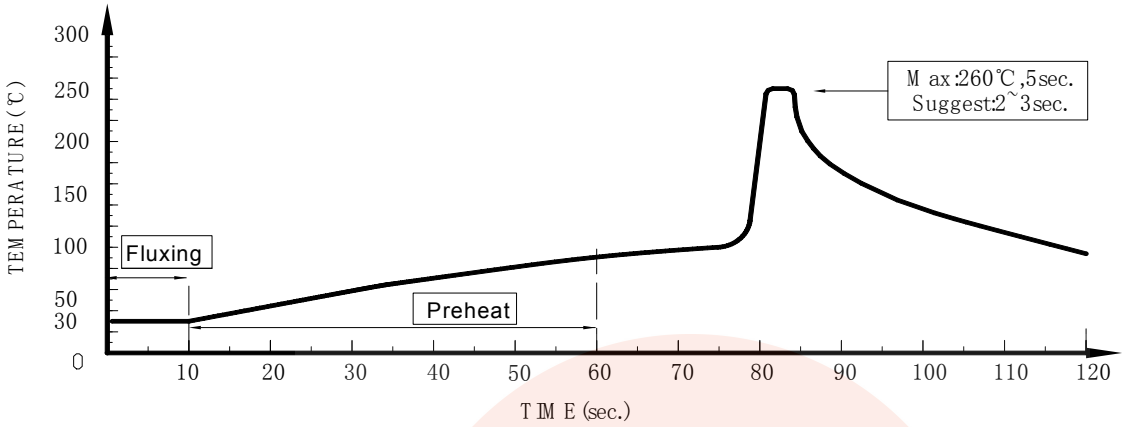



Fig.6 Radiation diagram



## ● Dip Soldering




1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature,especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs